

100mA Fixed Output LDO Regulator

BDxxFA1FP3

● General Description

BDxxFA1FP3 is an LDO regulator with output current capability of 0.1A. The output voltages are 3.3V, 5.0V, 5.4V, and 12.0V with $\pm 1\%$ accuracy. The SOT89-3 package is most suitable for heat dissipation. As protective function to prevent IC from destruction, this chip has built-in over current protection circuit to protect the device when output is shorted, and built-in thermal shutdown circuit to protect the IC during thermal over load conditions. This product can be used in wide variety of digital appliances. This regulator can use ceramic capacitor, which have smaller size and longer life than other capacitors.

● Features

- High accuracy output voltage
- Built-in Over current protection circuit (OCP)
- Built-in Temperature protection circuit (TSD)
- Soft start function

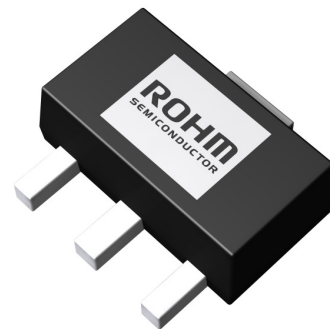
● Package

SOT89-3

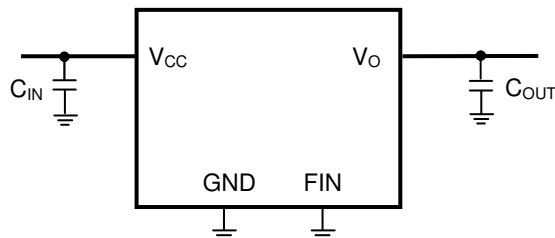
W(Typ.) D(Typ.) H(Max.)
 4.50mm x 4.15mm x 1.5mm

● Key Features

- Input power supply voltage range: $V_{in} + 3.0V$ to 25.0V
- Output voltage: 3.3V, 5.0V, 5.4V, 12.0V
- Output current: 0.1A (Max)
- Operating temperature range: $-25^{\circ}C$ to $+85^{\circ}C$



● Typical Application Circuit



C_{IN}, C_{OUT} : Ceramic Capacitor

● Ordering Information

B D x x F A 1 F P 3					-	TL
Part Number	Output voltage	Input Voltage	Output Current	Package	Packaging and forming specification	
	33: 3.3V 50: 5.0V 54: 5.4V J2: 12.0V	F: 30V	A1: 0.1A	FP3: SOT89-3	TL : Emboss tape reel	

● Block Diagram
BDxxFA1FP3

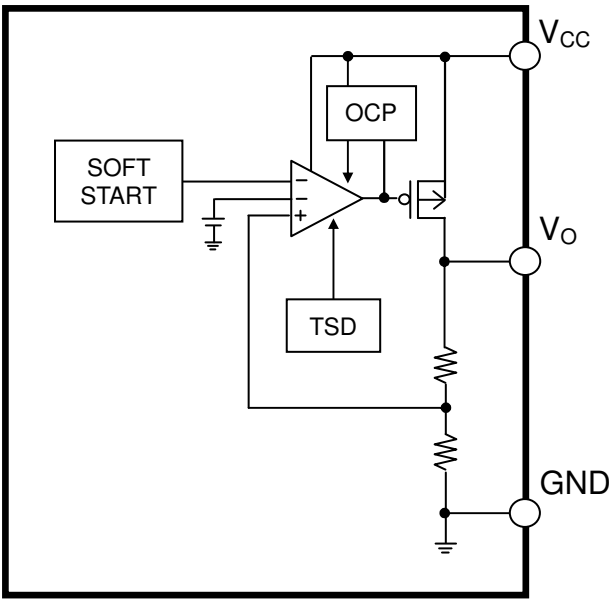
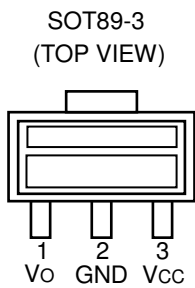


Fig. 1 Block Diagram

● Pin Configuration



● Pin Description

Pin No.	Pin name	Pin Function
1	Vo	Output pin
2	GND	GND pin
3	Vcc	Input pin
reverse	FIN	Substrate (Connect to GND)

● Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Power supply voltage		V _{CC}	30.0 * ¹	V
Output voltage		V _O	18	V
Power dissipation	SOT89-3	Pd* ²	1670 * ²	mW
Operating temperature range		T _{opr}	-25 to +85	°C
Storage temperature range		T _{stg}	-55 to +150	°C
Maximum junction temperature		T _{jmax}	+150	°C

*1 Not to exceed Pd.

*2 In case Ta ≥ 25°C (114.3mm × 76.2mm × 1.6mm when mounted on a 4-layer PCB based on JEDEC) is reduced by 11.5mW/°C

● Recommended Operating Conditions (Ta=25°C)

Parameter	Symbol	Min.	Max.	Unit
Input power supply voltage	V _{CC}	V _O +3.0	25.0	V
Output current	I _O	0.0	0.1	A

● Recommended Operating Condition

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Output Capacitor	C _{OUT}	0.3 * ³	1.0	-	μF	Ceramic capacitor recommended

*3 The minimum value of capacitor must met this specification over full operating conditions. (Ex: Temperature, DC bias)

● Electrical Characteristics (Unless otherwise specified, V_{CC}= 10.4V, V_O=5.4V, Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Bias current	I _{CC}	-	300	450	μA	
Line Regulation	Reg.I	-1	0.5	1	%	V _{CC} =(V _O +3V)→25.0V
Load Regulation	Reg I _O	-1.5	0.5	1.5	%	I _O =0→0.1A
Minimum dropout voltage	V _{CO}	-	2.0	3.0	V	I _O =0.1A
Output voltage	V _O	V _O × 0.99	V _O	V _O × 1.01	V	I _O =0A

●Performance Curve (Reference Data)

(Unless otherwise specified, Ta=25°C, Vcc=10.4V, Vo=5.4V, Cin=Cout=1uF)

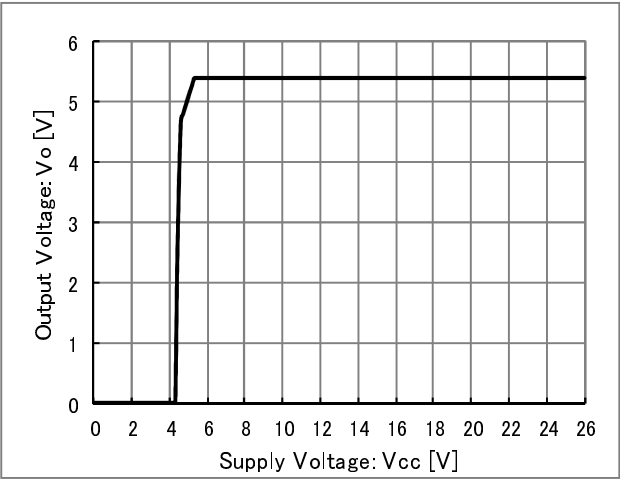


Fig 2. Vcc - Vo

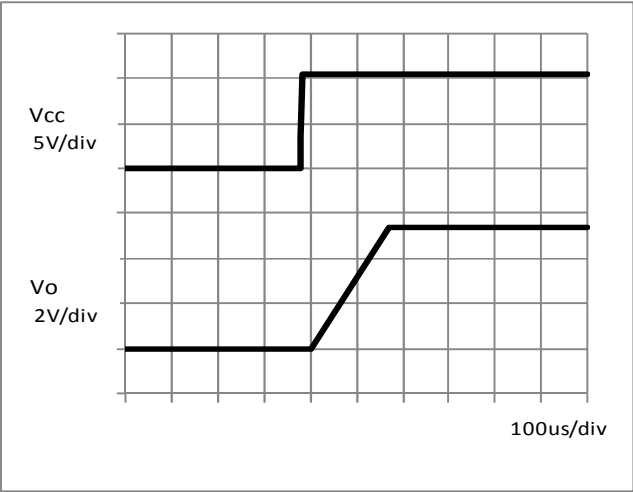


Fig 3. Input sequence
(Co = 1uF)

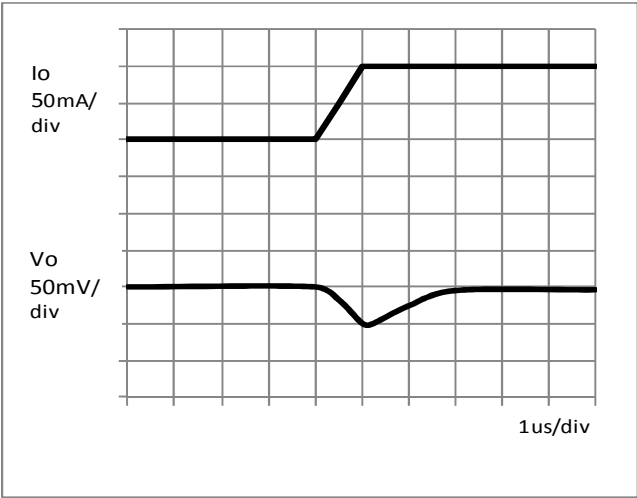


Fig 4. Transient Response
(Io = 0A→0.1A)
(Co = 1uF)

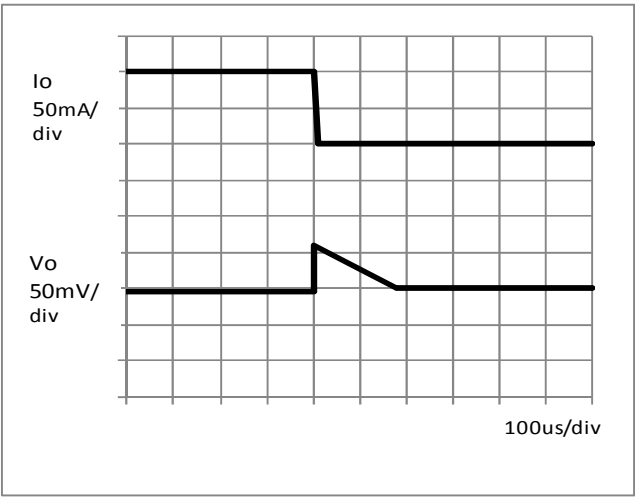


Fig 5. Transient Response
(Io = 0.1A→0A)
(Co = 1uF)

●Performance Curve (Reference Data)

(Unless otherwise specified, Ta=25°C, Vcc=10.4V, Vo=5.4V, Cin=Cout=1uF)

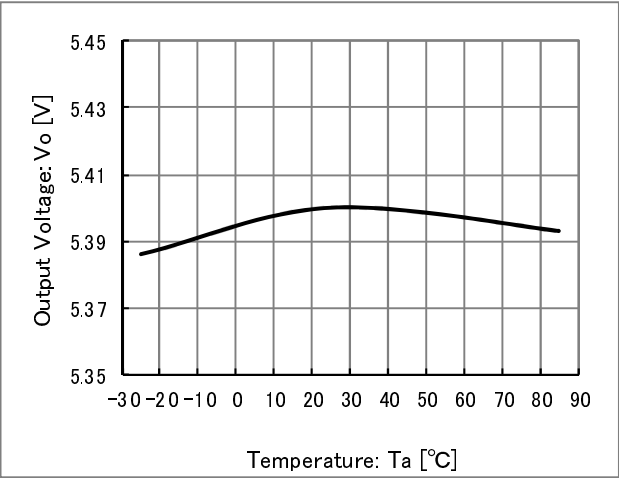


Fig 6. $T_a - V_o$
($I_o = 0\text{mA}$)

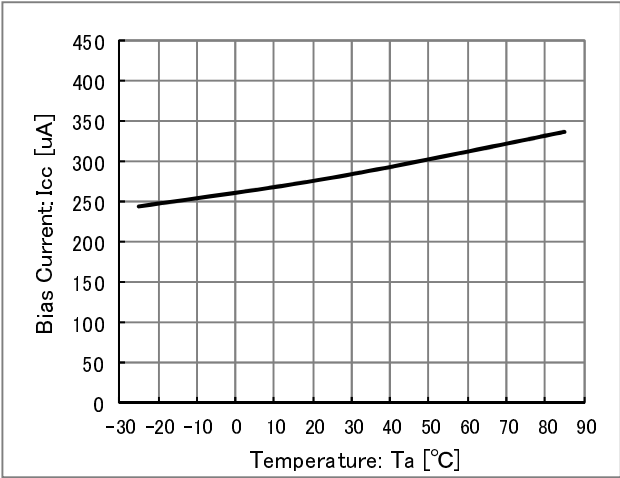


Fig 7. $T_a - I_{cc}$

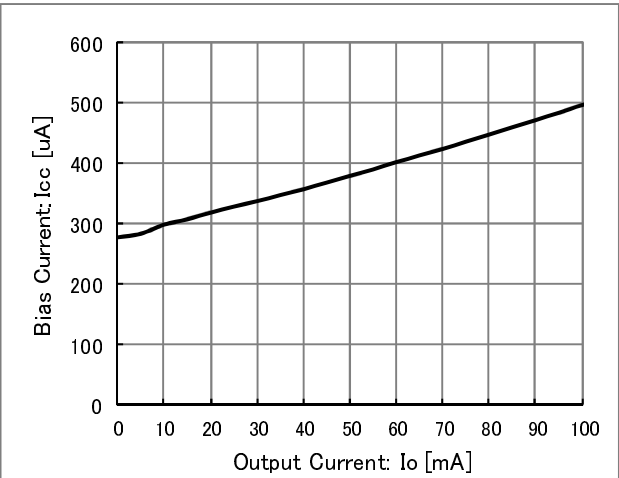


Fig 8. $I_o - I_{cc}$

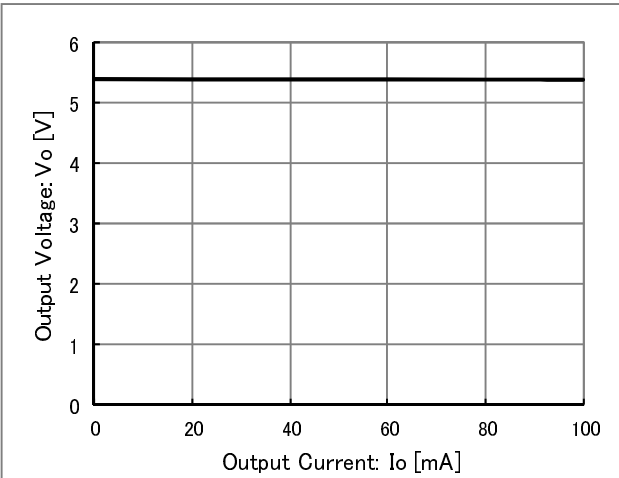


Fig 9. $I_o - V_o$

● Performance Curve (Reference Data)

(Unless otherwise specified, $T_a=25^\circ\text{C}$, $V_{cc}=10.4\text{V}$, $V_o=5.4\text{V}$, $C_{in}=C_{out}=1\mu\text{F}$)

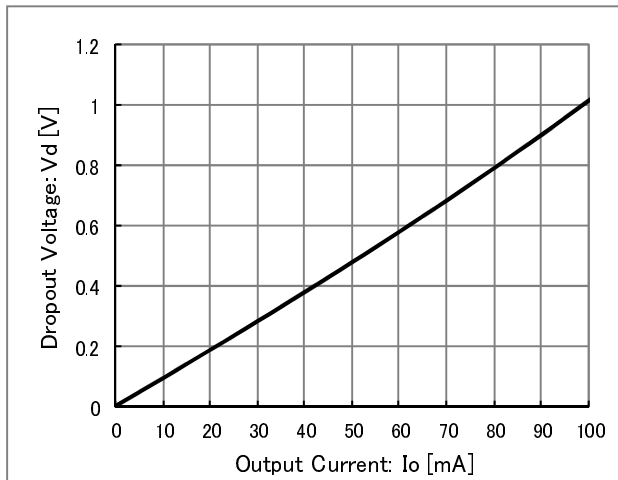


Fig 10. Minimum dropout Voltage

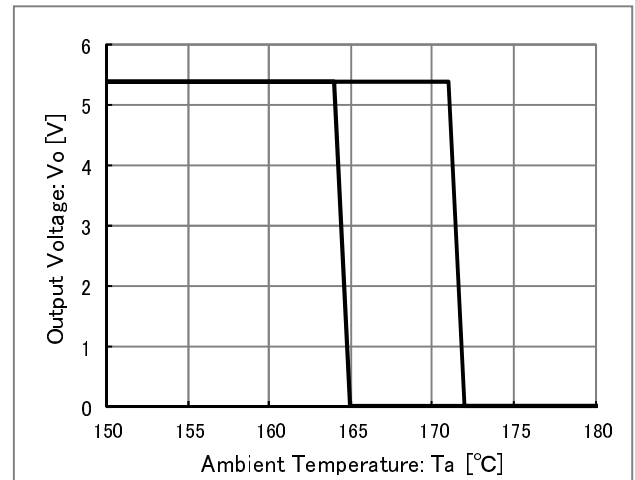


Fig 11. TSD
($I_o = 0\text{mA}$)

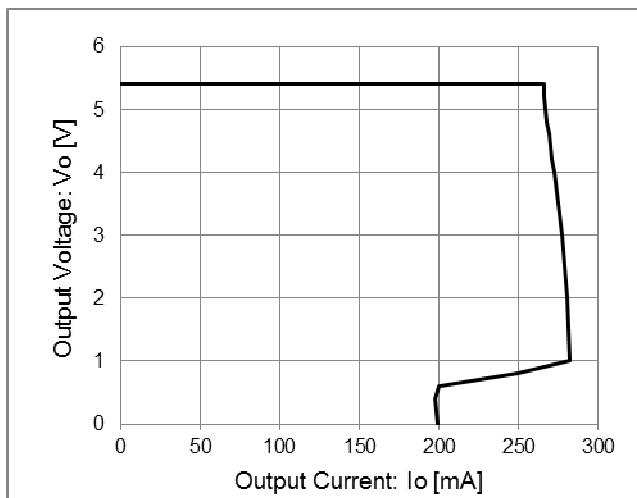


Fig 12. OCP

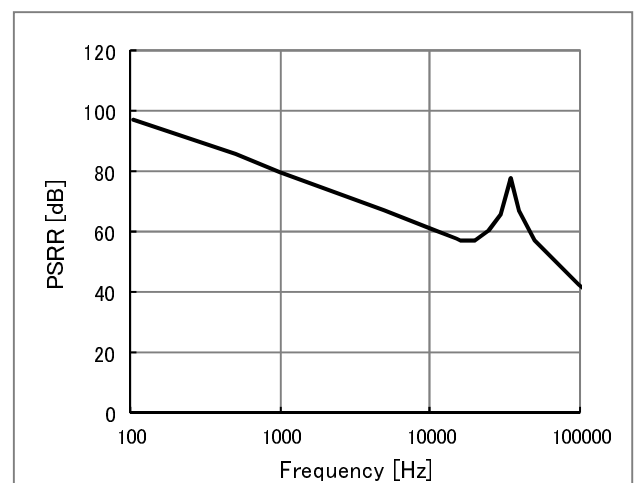


Fig 13. PSRR
($I_o = 0\text{mA}$)

●Performance Curve (Reference Data)
(Unless otherwise specified, Ta=25°C, Vcc=10.4V, Vo=5.4V, Cin=Cout=1uF)

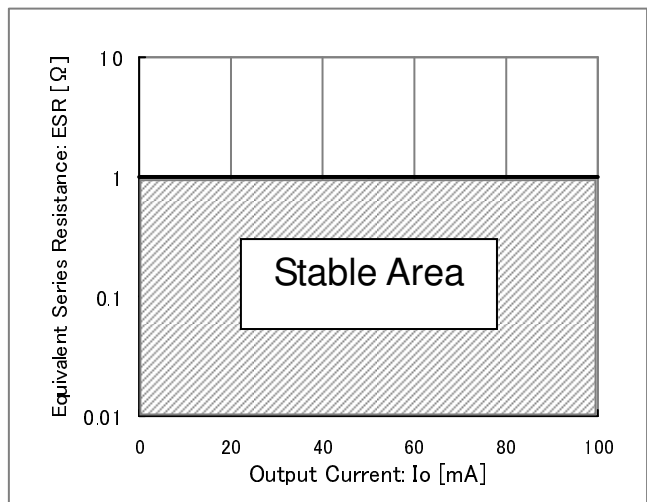
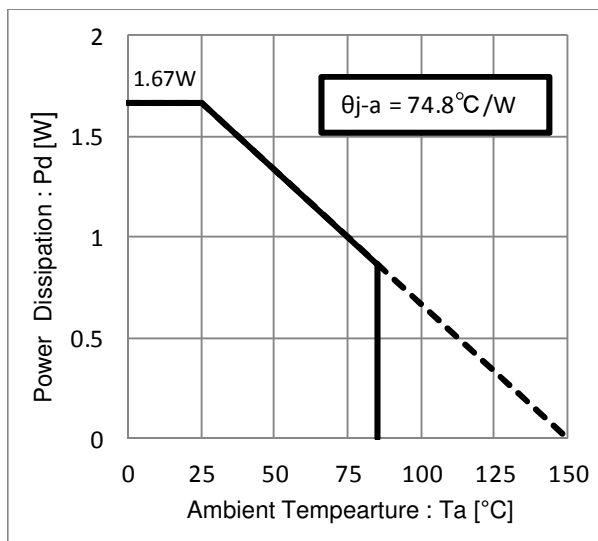


Fig14. ESR Stable Region

● Power Dissipation
 ◎SOT89-3



Measurement condition: mounted on 4-layer JEDEC standard board
 Board size: 114.3mm × 76.2mm × 1.6mm

When considering thermal design, operation should be maintained within the following conditions.
 (The temperature mentioned below is a guaranteed temperature, therefore, margins must be considered.)

1. Ambient temperature T_a is 85°C and below.
2. Junction temperature T_j is 150°C and below.

The junction temperature T_j can be determined as follows:
 Calculation based on ambient temperature T_a

$$T_j = T_a + \theta_{j-a} \times W$$

<Reference Value>

- θ_{j-a} : SOT89-3 74.8°C/W JEDEC standard 4 layers PCB
 Board size: 114.3mm × 76.2mm × 1.6mm

Most of the heat loss that occurs in BDxxFA1FP3 is generated from the output Pch FET. Power loss is determined by the product of voltage drop across $V_{cc}-V_o$ and the output current. Check the conditions of output voltage and output current to be used between $V_{cc}-V_o$ and compare with the power dissipation characteristics.

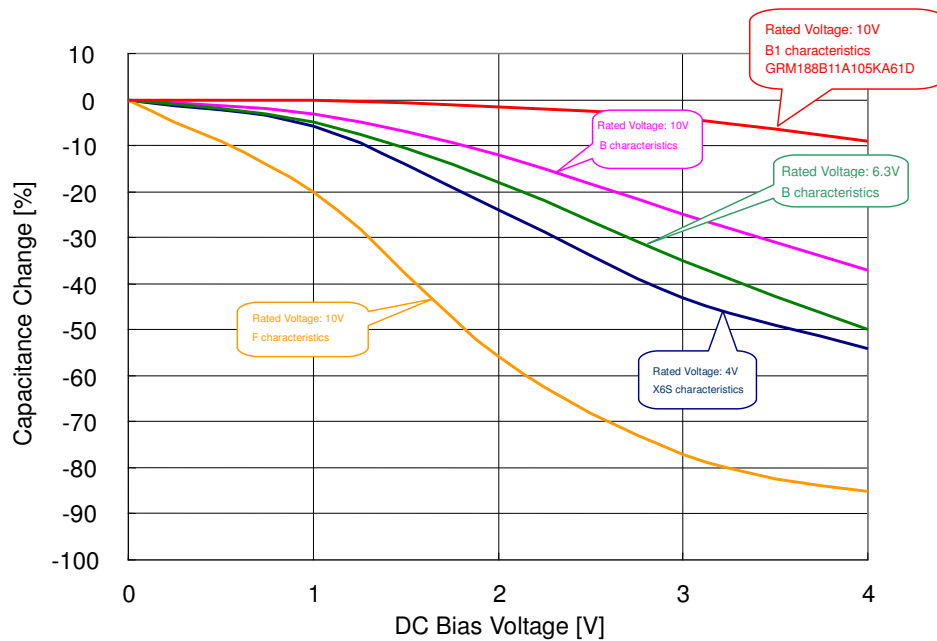
In addition, power dissipation may change significantly due to board conditions because BDxxFA1FP3 uses power package. It is important to consider the board size to be used before proceeding with the design.

$$\text{Power consumption [W]} = \{ \text{Input voltage (Vcc)} - \text{Output voltage (Vo)} \} \times \text{Output current (Io: Ave)}$$

● Input/Output Capacitor

It is recommended that a capacitor is placed close to pin between input pin and GND as well as output pin and GND. The input capacitor becomes more necessary when the power supply impedance is high or when the PCB trace has significant length. Moreover, the higher the capacitance of the output capacitor the more stable the output will be, even with load and line voltage variations. However, please check the actual functionality by mounting on a board for the actual application. Also, ceramic capacitors usually have different thermal and equivalent series resistance characteristics and may degrade gradually over continued use.

For additional details, please check with the manufacturer and select the best ceramic capacitor for your application.



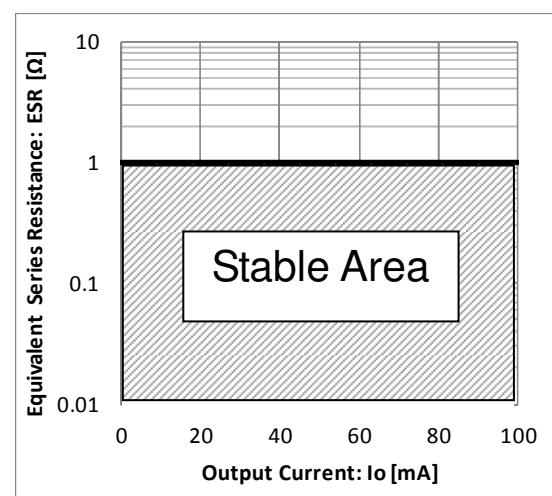
Ceramic Capacitor Capacitance Value— DC Bias Characteristics
(Characteristics Example)

● Output Capacitor Equivalent Series Resistance

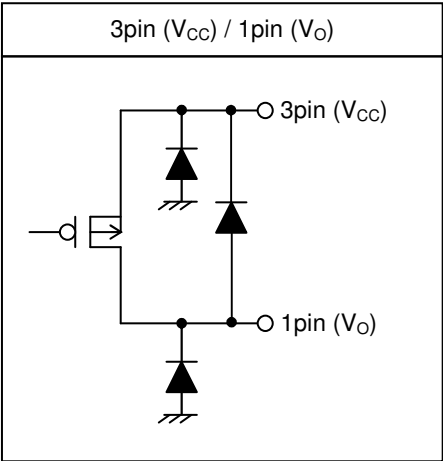
To prevent oscillation, please attach a capacitor between V_O and GND. Generally, capacitor has ESR (Equivalent Series Resistance). Operation will be stable in ESR- I_O range shown in the right.

The 1.0 μ F ceramic capacitor and resistor at output in this characteristic data are connected in series and measured. Generally, ESR of ceramic capacitor, tantalum capacitor and electrolytic capacitor is different. Check the ESR of capacitor to be used and use it within the range of stable region.

However, please take note that for the same value of capacitance of different electrolytic capacitor, ESR are not always the same. In addition, ESR characteristics may also change due to wiring impedance of board, input power impedance and load impedance; therefore check the behavior in actual application.



●Input/Output Equivalent Circuit



●Operational Notes

(1) Absolute Maximum Value Rate

Operating the IC over the absolute maximum ratings may damage the IC. In addition, it is impossible to predict all destructive situations such as short-circuit modes, open circuit modes, etc. Therefore, it is important to consider circuit protection measures, like adding a fuse, in case the IC is operated in a special mode exceeding the absolute maximum ratings.

(2) Reverse connection of power supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply terminals.

(3) Power supply line

Design the PCB layout pattern to provide low impedance ground and supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

(4) Ground voltage

The voltage of the ground pin must be the lowest voltage of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.

(5) Thermal consideration

Use a thermal design that allows for a sufficient margin by taking into account the permissible power dissipation (Pd) in actual operating conditions.

(6) Short between pins and mounting errors

Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.

(7) Operation under strong electromagnetic field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

(8) ASO

Operate the IC such that the output voltage, output current, and power dissipation are all within the Area of Safe Operation (ASO).

(9) Thermal shutdown circuit

The IC incorporates a built-in thermal shutdown circuit, which is designed to turn off the IC when the internal temperature of the IC reaches a specified value. It is not designed to protect the IC from damage or guarantee its operation. Do not continue to operate the IC after this function is activated. Do not use the IC in conditions where this function will always be activated.

	TSD ON Temperature [°C] (typ.)	Hysteresis Temperature [°C] (typ.)
BDxxFA1FP3	175	10

(10) Testing on application boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from electro static discharge, ground the IC during assembly and use similar precautions during transport and storage.

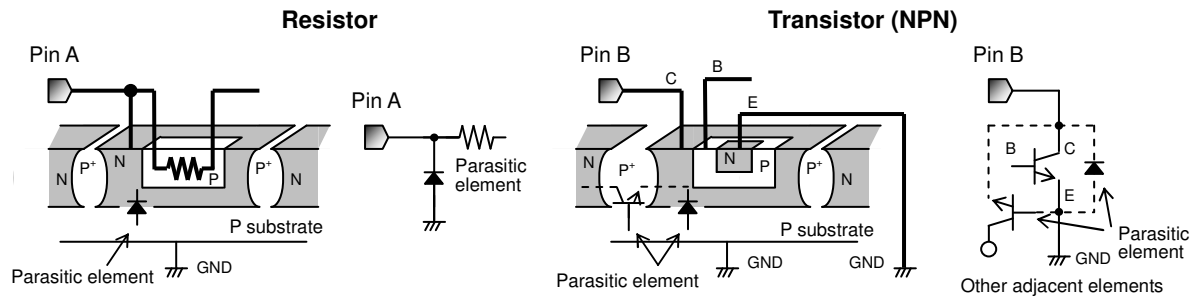
(11) Regarding input pins of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When $GND > Pin\ A$ and $GND > Pin\ B$, the P-N junction operates as a parasitic diode.

When $GND > Pin\ B$, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

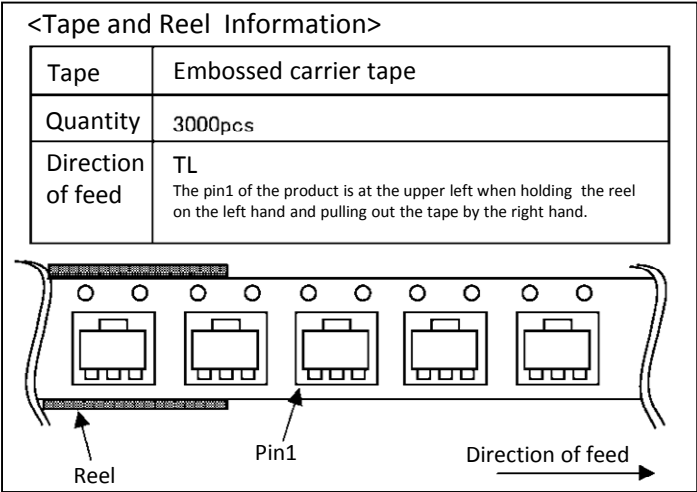
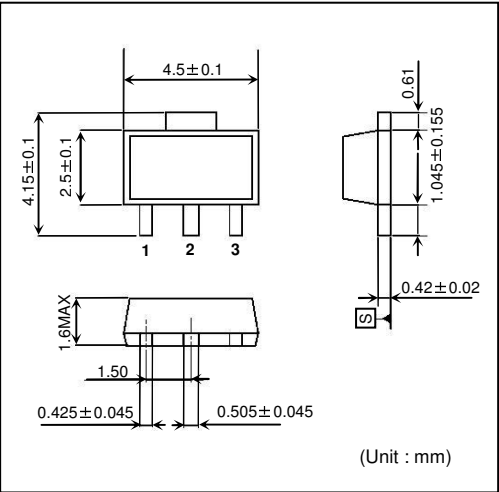


Example of monolithic IC structure

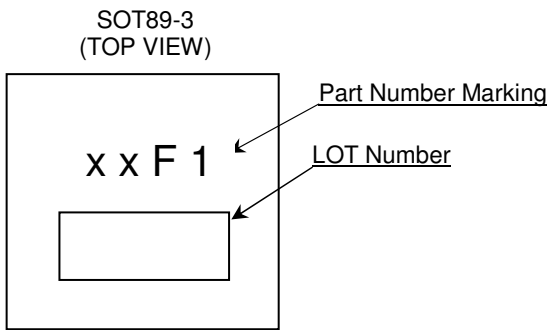
(12) Ground wiring pattern

When using both small-signal and large-current GND traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the GND traces of external components do not cause variations on the GND voltage. The power supply and ground lines must be as short and thick as possible to reduce line impedance.

●External Measurement Drawing and Packing Forming Specification



●Marking Diagram



● Revision History

Date	Revision	Revision contents
2014.02.04	001	New release
2014.10.31	002	Added 5.0V and 12V to output voltage line-up.

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
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 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
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- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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